

## Is Now Part of



# ON Semiconductor®

# To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at <a href="www.onsemi.com">www.onsemi.com</a>. Please email any questions regarding the system integration to Fairchild <a href="guestions@onsemi.com">guestions@onsemi.com</a>.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



FDMS86101

#### **April 2016**

# N-Channel PowerTrench<sup>®</sup> MOSFET 100 V, 60 A, 8 m $\Omega$

#### **Features**

- Max  $r_{DS(on)}$  = 8 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 13 A
- Max  $r_{DS(on)}$  = 13.5 m $\Omega$  at  $V_{GS}$  = 6 V,  $I_D$  = 9.5 A
- Advanced Package and Silicon combination for low r<sub>DS(on)</sub> and high efficiency
- MSL1 robust package design
- 100% UIL tested
- 100% Rg tested
- RoHS Compliant

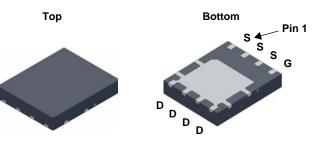


## **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

# **Application**

■ DC-DC Conversion





# 

# MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parame		Ratings	Units	
$V_{DS}$	Drain to Source Voltage			100	V
$V_{GS}$	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T <sub>C</sub> = 25 °C		60	
$I_D$	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	12.4	Α
	-Pulsed			200	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	173	mJ
В	Power Dissipation $T_C = 25 ^{\circ}C$			104	W
P <sub>D</sub> Power Dissipation		T <sub>A</sub> = 25 °C	(Note 1a)	2.5	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range			-55 to +150	°C

## **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity	
FDMS86101	FDMS86101	Power 56	13 "	12 mm	3000 units	

# **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		66		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V			800	nA
I <sub>GSS</sub>	Gate to Source Leakage Current, Forward	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

#### On Characteristics

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.0	2.9	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-9		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$		6.3	8	
r <sub>DS(on)</sub>	r <sub>DS(on)</sub> Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 9.5 \text{ A}$		8.4	13.5	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}, T_J = 125 ^{\circ}\text{C}$		10.9	14	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 13 A		45		S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 50 V V 0 V		2255	3000	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$		460	610	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1/11/12		30	45	pF
$R_g$	Gate Resistance		0.1	1.0	3.0	Ω

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		15	27	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 13 A,	11	20	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	27	44	ns
t <sub>f</sub>	Fall Time		7	13	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	39	55	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}  V_{DD} = 50 \text{ V},$	22	31	nC
Q <sub>gs</sub>	Gate to Source Charge	I <sub>D</sub> = 13 A	9.5		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		10.8		nC

## **Drain-Source Diode Characteristics**

LVeb Source to Drain Dioge Forward Voltage	Source to Drain Diode, Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2.1 \text{ A}$ (Note 2)		0.7	1.2	\/
	$V_{GS} = 0 \text{ V}, I_S = 13 \text{ A}$ (Note 2)		0.8	1.3	V	
t <sub>rr</sub>	Reverse Recovery Time	-I <sub>F</sub> = 13 A, di/dt = 100 A/μs		56	90	ns
Q <sub>rr</sub>	Reverse Recovery Charge			61	98	nC

#### Notes:

<sup>1.</sup> R<sub>0,JA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0,JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



 b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300  $\mu\text{s},$  Duty cycle < 2.0%.
- 3.  $E_{AS}$  of 173 mJ is based on starting  $T_J$  = 25 °C, L = 0.3 mH,  $I_{AS}$  = 34 A,  $V_{DD}$  = 75 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH,  $I_{AS}$  = 49 A.

# Typical Characteristics $T_J = 25$ °C unless otherwise noted

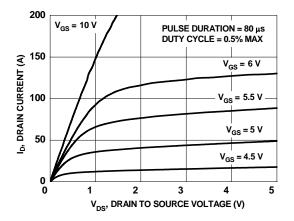


Figure 1. On Region Characteristics

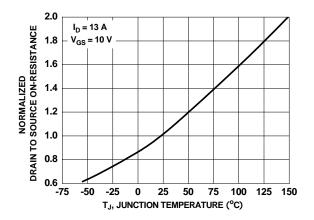


Figure 3. Normalized On Resistance vs Junction Temperature

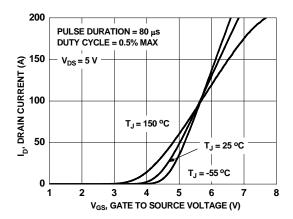


Figure 5. Transfer Characteristics

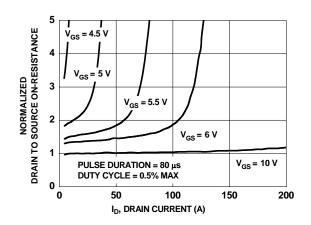


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

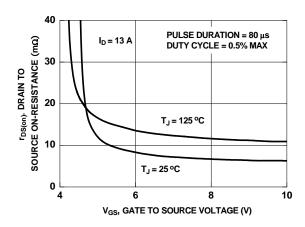


Figure 4. On-Resistance vs Gate to Source Voltage

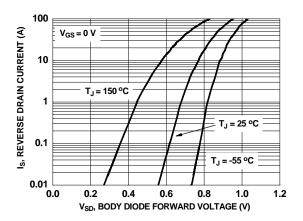


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

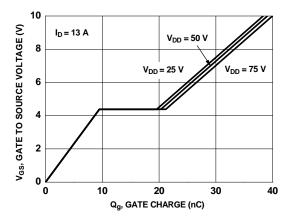


Figure 7. Gate Charge Characteristics

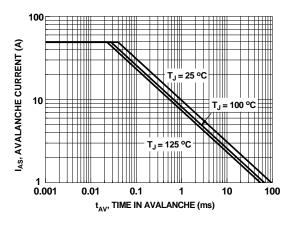


Figure 9. Unclamped Inductive Switching Capability

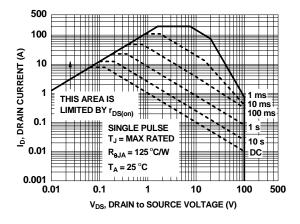


Figure 11. Forward Bias Safe Operating Area

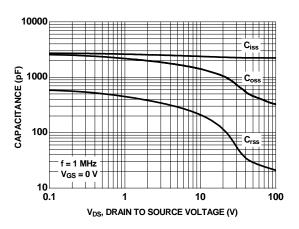


Figure 8. Capacitance vs Drain to Source Voltage

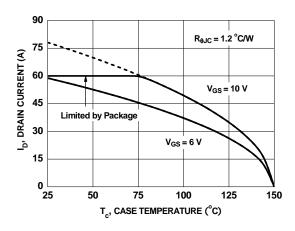


Figure 10. Maximum Continuous Drain Current vs Case Temperature

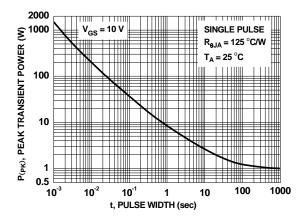


Figure 12. Single Pulse Maximum Power Dissipation

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

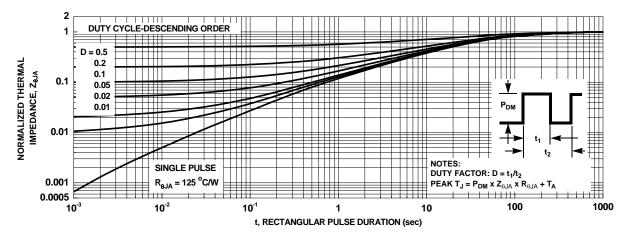
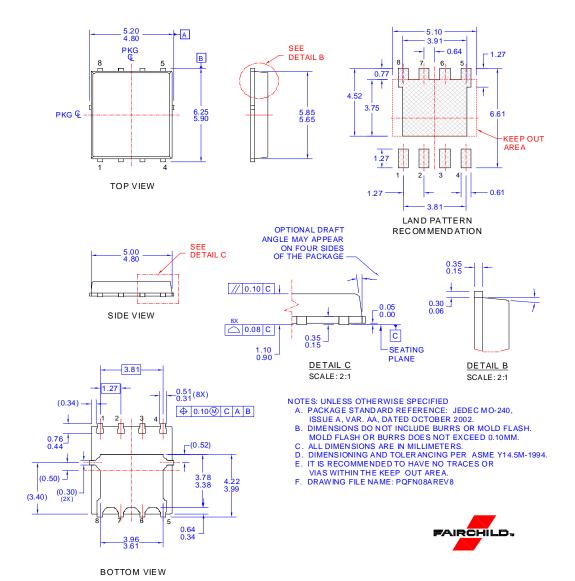


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

# **Dimensional Outline and Pad Layout**







#### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ AttitudeEngine™ Awinda® AX-CAP®+ BitSiC™ Build it Now™ CorePLUS™

CorePLUSTM
CorePOWERTM
CROSSVOLTTM
CTLTM

Current Transfer Logic™
DEUXPEED®
Dual Cool™

EcoSPARK®
EfficentMax<sup>TM</sup>
ESBC<sup>TM</sup>

Fairchild®

Fairchild Semiconductor® FACT Quiet Series™ FACT®

FACT<sup>®</sup>
FastvCore<sup>™</sup>
FETBench<sup>™</sup>
FPS<sup>™</sup>

F-PFS™ FRFET®

Global Power Resource<sup>SM</sup>

GreenBridge™ Green FPS™

Green FPS™ e-Series™ Gmax™

Gmax<sup>™</sup> GTO<sup>™</sup> IntelliMAX<sup>™</sup> ISOPLANAR<sup>™</sup>

Marking Small Speakers Sound Louder

and Better™ MegaBuck™

MICROCOUPLER™ MicroFET™

MicroPak™ MicroPak2™ MillerDrive™ MotionMax™ MotionGrid®

MTx<sup>®</sup>
MVN<sup>®</sup>
mWSaver<sup>®</sup>
OptoHiT<sup>TM</sup>
OPTOLOGIC<sup>®</sup>

OPTOPLANAR®

® Power Supply WebDesigner™

PowerTrench<sup>©</sup> PowerXS™

Programmable Active  $\mathsf{Droop}^{\mathsf{TM}}$ 

QFĔT<sup>®</sup>
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™

OTTM-3 VisualM DTTM-6 Voltagei DTTM-8 XSTM OS® XsensTM TTM 仙童®

SYSTEM ®\*
GENERAL
Tiny Boost®

TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TinyPOPTO™
TinyPOWer™
TinyPWM™
TinyWire™
TranSiC™
TriFault Detect™
TRUECURRENT®\*\*

Scroes\*
UHC®
Ultra FRFET\*\*
UniFET\*\*
VCX\*\*
VisualMax\*\*
VoltagePlus\*\*
XS\*\*
Xsens\*\*

\*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT <a href="http://www.fairchildsemi.com">http://www.fairchildsemi.com</a>. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### **AUTHORIZED USE**

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

#### ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Terms of Use

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild bistributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 177



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:

FDMS86101